

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	48	(wafer) and (thermosetting near resin) and encapsulation	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM TDB	2001/11/1 4 16:36
2	BRS	L2	0	(wafer) and (thermosetting near resin) and encapsulation and polish and expose and bump	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM TDB	2001/11/1 4 16:37
3	BRS	L3	0	(wafer) and (thermosetting near resin) and encapsulation and polish	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM TDB	2001/11/1 4 16:38
4	BRS	L4	1	(wafer) and (thermosetting near resin) and encapsulation and CMP	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM TDB	2001/11/1 4 16:42

	Type	L #	Hits	Search Text	DBs	Time Stamp
5	BRS	L5	1	(wafer) and (thermosetting near resin) and encapsulation and (CMP or Chemical near mechanical near polishing)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM TDB	2001/11/1 4 16:43
6	BRS	L6	281	438/612 and 438/613	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM TDB	2001/11/1 4 16:59
7	BRS	L7	3	"6281591"	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM TDB	2001/11/1 4 16:48